Compliant with IEC 62474/ D9.00 Compliant to IEC 61249-2-21:2003

MICROCHIP			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)				J-STD-609A Product Marking and/or Pkg. Labeling e4
Semiconductor Device Type:	D/A	003 SOT-23 NiPdAu "Contained In"	% Total		1					
Basic Substance	CAS Number	Sub-Component	Weight	mg/part	ppm	5.54	(mg) Total	Mold Compound	% ot Total Weight	58.27
Silica, vitreous	60676-86-0	Mold Compound	49.530	4.705	495,295		Silica, vitreous	60676-86-0	85.00	
Epoxy Resin	Trade Secret	Mold Compound	3.569	0.339	35,690		Epoxy Resin	Trade Secret	6.13	
Phenolic Resin	Trade Secret	Mold Compound	3.569	0.339	35,690		Phenolic Resin	Trade Secret	6.13	
Epoxy, Cresol Novolac	29690-82-2	Mold Compound	1.428	0.136	14,276		Epoxy, Cresol Novolac	29690-82-2	2.45	
Carbon Black	1333-86-4	Mold Compound	0.175	0.017	1,748		Carbon Black	1333-86-4	0.30	
Copper	7440-50-8	Lead Frame	34.454	3.273	344,539			Total	100.00	
Iron	7439-89-6	Lead Frame	0.814	0.077	8,144	3.36	(mg) Total	Lead Frame	% of Total Weight	35.41
Phosphorous	7723-14-0	Lead Frame	0.089	0.008	885		Copper	7440-50-8	97.30	
Zinc (Metal)	7440-66-6	Lead Frame	0.053	0.005	531		Iron	7439-89-6	2.30	
Silver	7440-22-4	Die Attach	0.968	0.092	9.675		Phosphorous	7723-14-0	0.25	
Epoxy Resin	9003-36-5	Die Attach	0.323	0.031	3,225		Zinc (Metal)	7440-66-6	0.15	
Silicon	7440-21-3	Chip (Die)	3.300	0.314	33.000		Ziiio (iviotal)	Total	100.00	
Gold	7440-57-5	Wire Bond	0.410	0.039	4.100	0.12	(mg) Total	Die Attach	% of Total Weight	1.29
Nickel	7440-02-0	Plating on external leads (pins)	1.188	0.113	11.880	0.12	Silver	7440-22-4		1.23
Palladium	7440-02-0		0.066	0.006	660			9003-36-5	75.00	
		Plating on external leads (pins)					Epoxy Resin		25.00	
Gold	7440-57-5	Plating on external leads (pins)	0.066	0.006	660			Total	100.00	
		TOTALS:	100.000	9.500	1,000,000	0.31	Total (mg)	Chip (Die)	% of Total Weight	3.30
	aterials comply wi	g Total Mass th EU Directives: 2002/95/EC (27 January 2003)			,,	0.31	Total (mg) Doped Silicon	Chip (Die) 7440-21-3 Total	% of Total Weight 100.00 100.00	3.30
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015/863/EU (31 March 2015) and 2002/53/EC (E bliance with the above EU Directives has been nemical substance is absent from the list abov bothip Technology Incorporated's knowledge a	aterials comply wi End-of-Life Vehicle verified via intern ve, the chemical so nd belief as of the	g Total Mass th EU Directives: 2002/95/EC (27 January 2003) a es (ELV) without exemption (zero)	& Directive 201 analytical test of the community of the c	1/65/EU (08 Judata. levice and, to the the unavoida	une 2011)		Doped Silicon	7440-21-3 Total	100.00	
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